

Title (en)

METHOD FOR PRODUCING A THREE-DIMENSIONAL CONDUCTOR TRACE STRUCTURE AND A CONDUCTOR TRACE STRUCTURE PRODUCED ACCORDING TO THIS METHOD

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER DREIDIMENSIONALEN LEITERBAHNSTRUKTUR SOWIE EINE NACH DIESEM VERFAHREN HERGESTELLTE LEITERBAHNSTRUKTUR

Title (fr)

PROCEÉDÉ DE FABRICATION D'UNE STRUCTURE DE PISTES CONDUCTRICES TRIDIMENSIONNELLE ET STRUCTURE DE PISTES CONDUCTRICES FABRIQUÉE SELON CE PROCÉDÉ

Publication

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Application

**EP 13740202 A 20130613**

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Abstract (en)

[origin: WO2013189486A1] The invention relates to a method for producing a conductor trace structure (4) on a dielectric carrier material (1). The carrier material (1) is first furnished with a flat coating (2). Nanoscale particles containing a substantial material content of metal oxides such as copper oxides, which are coated with a suitable reduction agent, are contained in the coating (2). Then, the coating (2) is exposed selectively to an electromagnetic radiation from a laser (3). Due to selective action of radiation, this results in a sintering of particles contained in or generated in situ in the coating (2), producing the conductive trace structure (4).

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

See references of WO 2013189486A1

Citation (examination)

- US 2008286488 A1 20081120 - LI YUNJUN [US], et al
- US 2004137710 A1 20040715 - GRIGOROPOULOS CONSTANTINE P [US], et al

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